

IN THE CLAIMS

1. (currently amended) A connection component comprising:

a dielectric element having a first surface and a second surface;

conductive pads on the first surface of the dielectric element, each conductive pad having a center;

conductive vias electrically connected to said conductive pads and extending toward the second surface of said dielectric element, each said via having an opening at one of said conductive pads, wherein at least one of the via openings is offset from the center of at least one of said conductive pads; and

a fusible mass positioned atop the at least one of said conductive pads having the offset via opening, wherein said fusible mass is at least partially reflowed for permanently attaching said fusible mass to the at least one of said conductive pads and wherein the offset via opening is at least partially exposed.

2. (original) The connection component as claimed in claim 1, wherein each said via has a center, and wherein the centers of one or more of said vias are offset from the centers of one or more of said conductive pads.

3. (original) The method as claimed in claim 1, wherein each said via has a center, and wherein the centers of said vias are offset from the centers of said conductive pads.

4. (original) The method as claimed in claim 1, wherein each said via has a closed end opposite the opening thereof and adjacent the second surface of said dielectric element.

5. (currently amended) The connection component as claimed in claim 1, wherein further comprising said a fusible mass is attached to the first surface of said dielectric element the at least one of said conductive pads having the offset via opening, adjacent to the at least one offset via opening.

6. (original) The connection component as claimed in claim 1, wherein said dielectric element is a flexible dielectric sheet.

7. (original) The connection component as claimed in claim 1, further comprising conductive traces overlying the second surface of said dielectric element, said conductive traces being electrically interconnected with said conductive vias.

8. (original) The connection component as claimed in claim 8, wherein said vias extend in a direction that intersects planes defined by the first and second surfaces of said dielectric element.

9. (original) The connection component as claimed in claim 1, wherein said conductive vias comprise a conductive metal.

10. (original) The connection component as claimed in claim 1, wherein said conductive vias are covered by a conductive polymer.

11. (new) A connection component comprising:  
a dielectric element having a first surface and a second surface;

a conductive pad having a center on the first surface of the dielectric element;

a conductive via electrically connected to the conductive pad and extending toward the second surface of the dielectric element, wherein the via has an opening at the conductive pad and is offset from the center thereof; and

a fusible mass in contact with the conductive pad, wherein said fusible mass does not completely obstruct said via opening so that said via opening is at least partially exposed.

12. (new) The connection component as claimed in claim 11, further comprising a flux material in contact with said fusible mass.

13. (new) The connection component as claimed in claim 12, further comprising a flux material in contact with said conductive pad.

14. (new) The connection component as claimed in claim 11, wherein said fusible mass is at least partially liquid.

15. (new) The connection component as claimed in claim 11, wherein said fusible mass is at least partially liquid and partially solid.

16. (new) The connection component as claimed in claim 11, wherein said fusible mass comprises a metallic solder material.

17. (new) A connection component comprising:  
a dielectric element having a first surface and a second surface;

a conductive pad having a center on the first surface of the dielectric element;

a conductive via electrically connected to the conductive pad and extending toward the second surface of the dielectric element, wherein the via has an opening at the conductive pad and is offset from the center thereof; and

a flux material in contact with the conductive pad, wherein said flux material does not completely obstruct said via opening so that said via opening is at least partially exposed.